Serial No. 09/882,141



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PATENT APPLICATION

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Applicant(s): Wang, Y.

Case:

AM1562D1

Conf No.: 8856

Serial No.:

09/882,141

Filed: June 15, 2001

Examiner:

Umez Eronini, L. Group Art Unit:

1765

Title:

METHOD OF ETCHING HIGH ASPECT RATIO OPENINGS IN SILICON

ASSOCIATE POWER OF ATTORNEY

COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, VA 22313-1450

SIR:

Applicants' attorney, Donald Verplancken, hereby appoints:

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as Associate Attorneys with full powers to prosecute this application, to make alterations and amendments therein, to inspect and make copies thereof and of any papers in any appellate and inter-party proceedings in which it may be involved, and to transact all business in the United States Patent and Trademark Office connected therewith.

Please direct all correspondence relating to this application to:

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Respectfully submitted,

12/24/03

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date: 1-5-2004

Barbara J. Jackson